

Title (en)

CONTACT MODULE FOR CONTACTING PRINTED CIRCUIT BOARDS

Title (de)

KONTAKTMODUL ZUR KONTAKTIERUNG VON LEITERPLATTEN

Title (fr)

MODULE DE CONTACT POUR LA MISE EN CONTACT DE CARTES DE CIRCUITS IMPRIMÉS

Publication

**EP 4066268 A1 20221005 (DE)**

Application

**EP 21766675 A 20210830**

Priority

- EP 2021073836 W 20210830
- DE 102020132937 A 20201210

Abstract (en)

[origin: WO2022122198A1] The invention relates to a circuit board contact assembly (1) for making contact between a first printed circuit board (PCB1) and a second printed circuit board (PCB2), comprising at least two circuit board contacts (10) which have a connecting portion (11) at one contacting end thereof and a press-in zone (12) at the second contacting end thereof; at least one sealing member (20) which entirely surrounds the contacts in a central portion is provided between the connecting portion (11) and the press-in zone (12), the connecting portion (11) protruding from one lateral surface (21) of the sealing member (20) and the press-in zones (12) protruding from another lateral surface (22) of the sealing member (20).

IPC 8 full level

**H01H 1/58** (2006.01); **H01H 13/10** (2006.01)

CPC (source: EP)

**H01H 1/5805** (2013.01); **H01H 9/0264** (2013.01); **H01H 13/10** (2013.01); **H01H 1/44** (2013.01); **H01H 13/06** (2013.01); **H01H 13/52** (2013.01); **H01H 2009/048** (2013.01); **H01R 12/585** (2013.01); **H01R 12/737** (2013.01)

Citation (search report)

See references of WO 2022122198A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2022122198 A1 20220616**; DE 102020132937 A1 20220615; EP 4066268 A1 20221005; EP 4066268 B1 20240320

DOCDB simple family (application)

**EP 2021073836 W 20210830**; DE 102020132937 A 20201210; EP 21766675 A 20210830